

SOT109-3

plastic small outline package; 16 leads; body width 3.9 mm;
body thickness 1.47 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	SO16
Package type industry code	SO16
Package style descriptive code	SO (small outline)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-012AC
Mounting method type	S (surface mount)
Issue date	19-2-2003

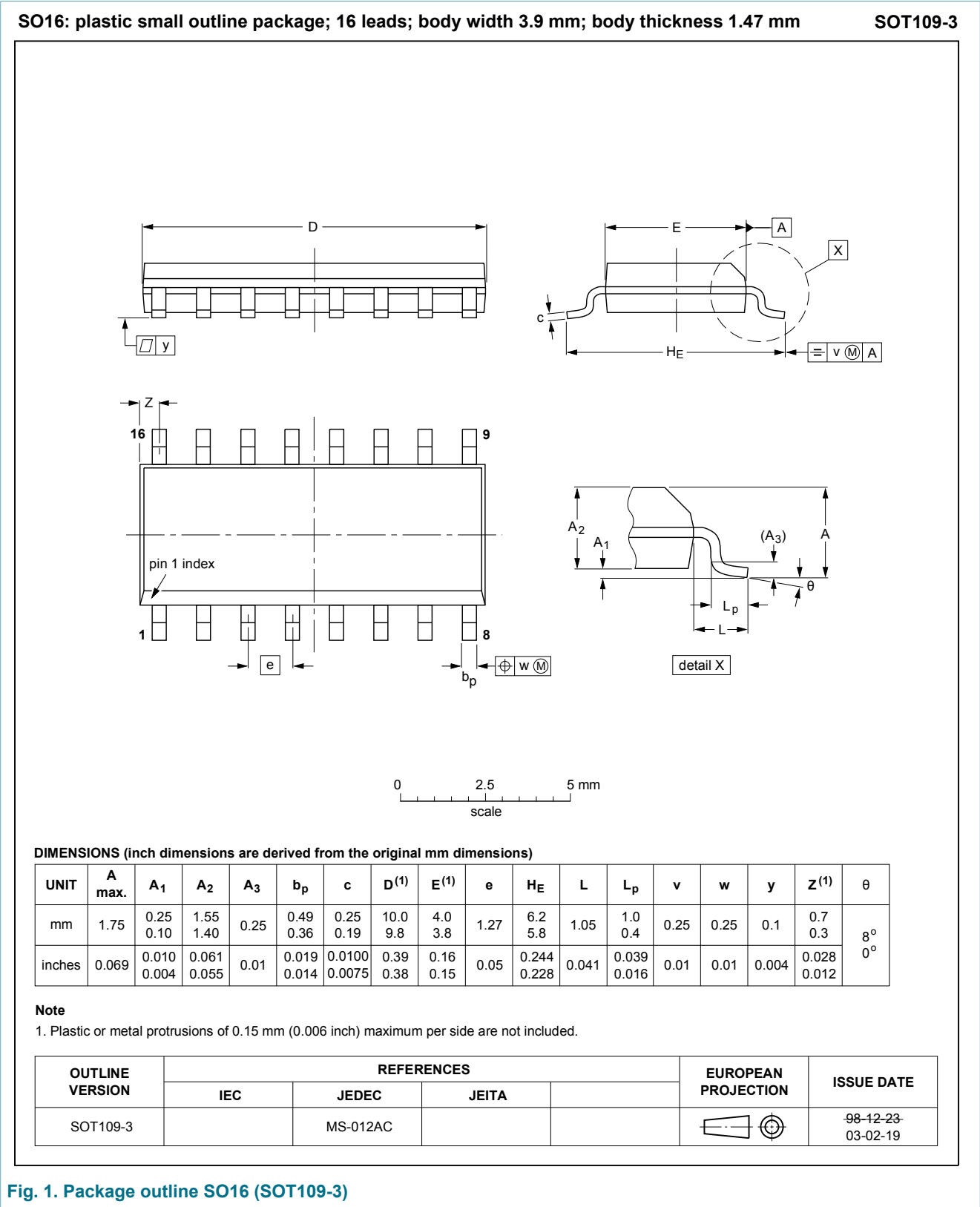
Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		9.8	-	9.9	10	mm
E	package width		3.8	-	3.9	4	mm
A	seated height		[tbd]	-	1.75	1.75	mm
A ₂	package height		1.4	-	1.47	1.55	mm
e	nominal pitch		-	-	1.27	-	mm
n ₂	actual quantity of termination		-	-	16	-	



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2. Package outline



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3. Soldering

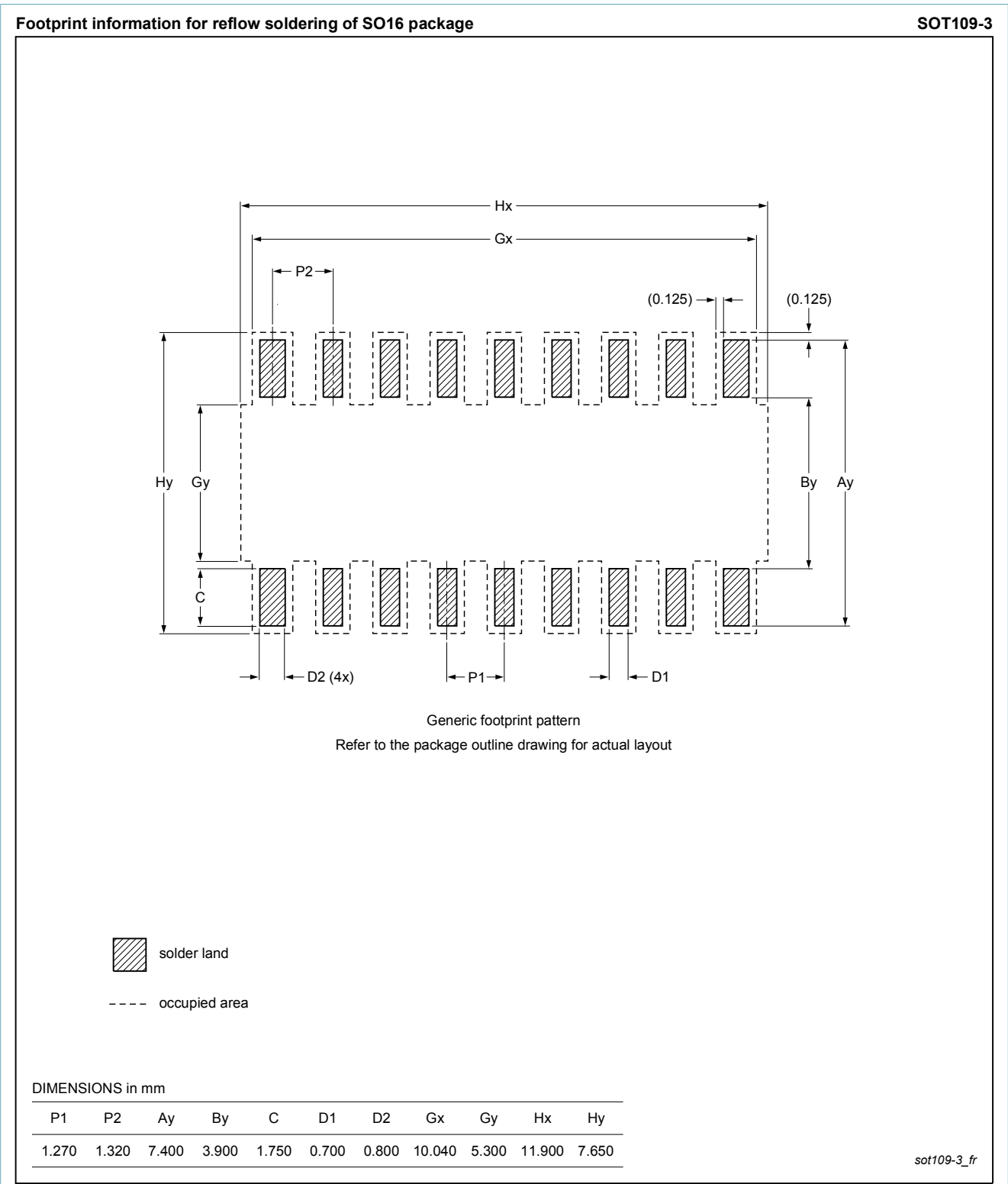


Fig. 2. Reflow soldering footprint for SO16 (SOT109-3)

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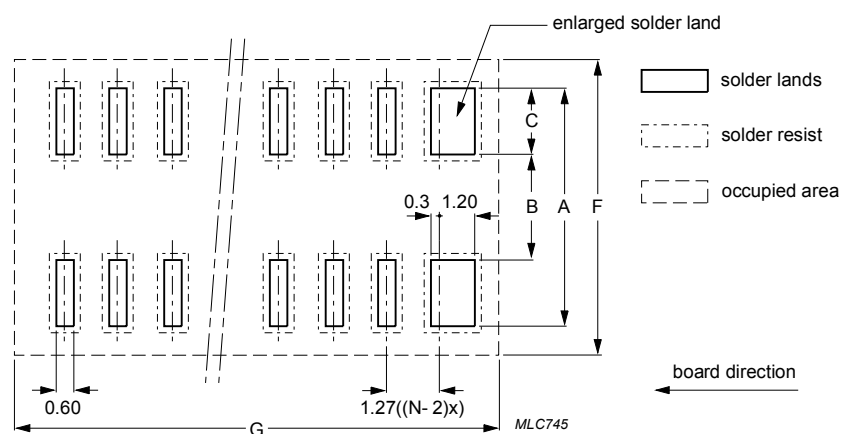


Fig. 3. Wave soldering footprint for SO16 (SOT109-3)

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4. Legal information

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